

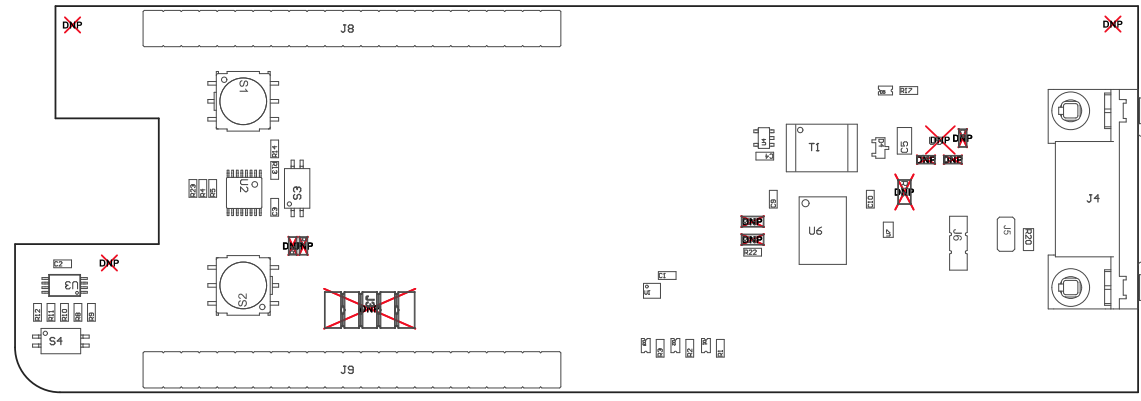
- These assemblies must be clean and free of contaminants.
- These assemblies are ESD sensitive.

ZZ3

ZZ1

ZZ2

Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.



ZZ4 ■ These assemblies must comply with upstream standards IPC-A-610 Class 2, unless otherwise specified.

LBL1

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

BOARD #: TIDA-01406 REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-01406

PLOT NAME = Bottom Assembly Drawing

GENERATED : 3/9/2017 11:16:47 AM

TEXAS INSTRUMENTS

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